

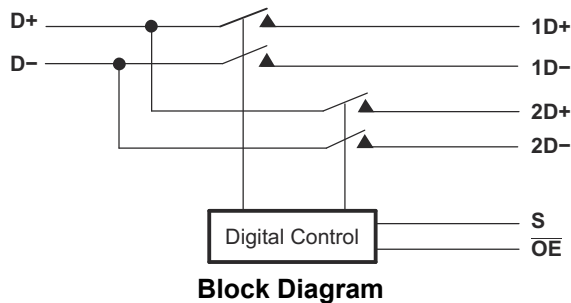
# TS3USB221 High-Speed USB 2.0 (480Mbps) 1:2 Multiplexer or Demultiplexer Switch with Single Enable

## 1 Features

- $V_{CC}$  operation from 2.3V and 3.6V
- $V_{IO}$  accepts signals up to 5.5V
- 1.8V compatible control-pin inputs
- Low-power mode when  $\overline{OE}$  is disabled ( $1\mu A$ )
- $R_{ON} = 6\Omega$  maximum
- $\Delta r_{ON} = 0.2\Omega$  typical
- $C_{IO(ON)} = 6\text{pf}$  maximum
- Low power consumption ( $30\mu A$  maximum)
- ESD > 2000V Human-Body Model (HBM)
- High bandwidth (1GHz typical)

## 2 Applications

- Routes signals for USB 1.0, 1.1, and 2.0
- Mobile industry processor interface (MIPI™) signal routing
- MHL 1.0



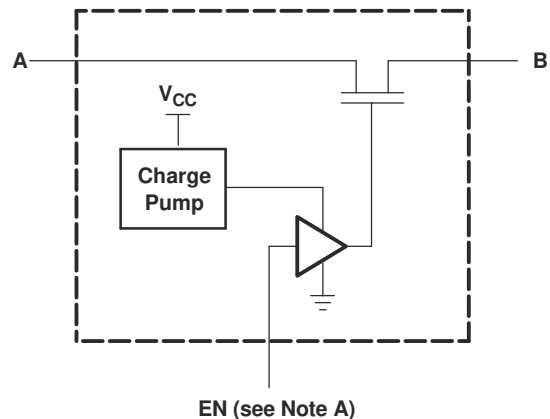
## 3 Description

The TS3USB221 is a high-bandwidth switch specially designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os. The wide bandwidth (1.1GHz) of this switch allows signals to pass with minimum edge and phase distortion. The device multiplexes differential outputs from a USB host device to one of two corresponding outputs. The switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. The TS3USB221 is designed for low bit-to-bit skew and high channel to channel noise isolation. The TS3USB221 is also compatible with various standards, such as high-speed USB 2.0 (480Mbps).

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
TS3USB221	DRC (VSON, 10)	3mm × 3mm
	RSE (UQFN, 10)	2mm × 1.5mm

- (1) For all available packages, see [Section 11](#).  
 (2) The package size (length × width) is a nominal value and includes pins, where applicable.



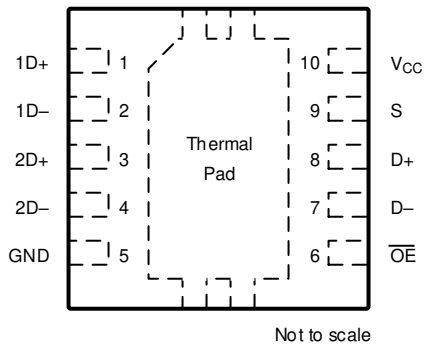
- A. EN is the internal enable signal applied to the switch.



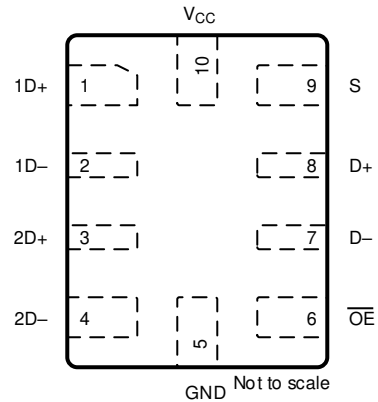
## Table of Contents

<b>1 Features</b> .....	1	7.1 Overview.....	12
<b>2 Applications</b> .....	1	7.2 Functional Block Diagram.....	12
<b>3 Description</b> .....	1	7.3 Feature Description.....	12
<b>4 Pin Configuration and Functions</b> .....	3	7.4 Device Functional Modes.....	12
<b>5 Specifications</b> .....	4	<b>8 Application and Implementation</b> .....	13
5.1 Absolute Maximum Ratings.....	4	8.1 Application Information.....	13
5.2 ESD Ratings.....	4	8.2 Typical Application.....	13
5.3 Recommended Operating Conditions.....	4	8.3 Power Supply Recommendations.....	15
5.4 Thermal Information.....	5	8.4 Layout.....	15
5.5 Electrical Characteristics.....	5	<b>9 Device and Documentation Support</b> .....	17
5.6 Dynamic Electrical Characteristics, $V_{CC} = 3.3V \pm 10\%$ .....	6	9.1 Documentation Support.....	17
5.7 Dynamic Electrical Characteristics, $V_{CC} = 2.5V \pm 10\%$ .....	6	9.2 Receiving Notification of Documentation Updates....	17
5.8 Switching Characteristics, $V_{CC} = 3.3V \pm 10\%$ .....	6	9.3 Support Resources.....	17
5.9 Switching Characteristics, $V_{CC} = 2.5V \pm 10\%$ .....	6	9.4 Trademarks.....	17
5.10 Typical Characteristics.....	7	9.5 Electrostatic Discharge Caution.....	17
<b>6 Parameter Measurement Information</b> .....	8	9.6 Glossary.....	17
<b>7 Detailed Description</b> .....	12	<b>10 Revision History</b> .....	17
		<b>11 Mechanical, Packaging, and Orderable Information</b> .....	18

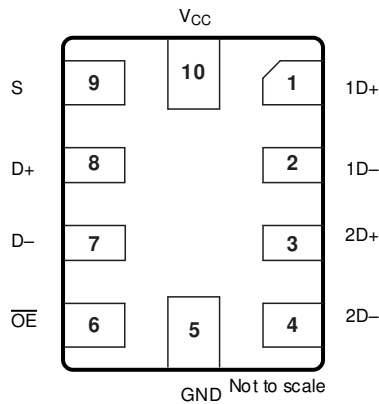
## 4 Pin Configuration and Functions



**Figure 4-1. DRC Package, 10-Pin VSON (Top View)**



**Figure 4-2. RSE Package, 10-Pin UQFN (Top View)**



**Figure 4-3. RSE Package, 10-Pin UQFB (Bottom View)**

**Table 4-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
1D+	1	I/O	USB port 1
1D-	2	I/O	
2D+	3	I/O	
2D-	4	I/O	
GND	5	—	Ground
OE	6	I	Bus-switch enable
D-	7	I/O	Common USB port
D+	8	I/O	
S	9	I	Select input
V <sub>CC</sub>	10	—	Supply voltage

(1) I = input, O = output

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	-0.5	4.6	V
V <sub>IN</sub>	Control input voltage <sup>(2) (3)</sup>	-0.5	7	V
V <sub>I/O</sub>	Switch I/O voltage <sup>(2) (3) (4) (6)</sup>	-0.5	7	V
I <sub>IK</sub>	Control input clamp current	V <sub>IN</sub> < 0		-50 mA
I <sub>I/OK</sub>	I/O port clamp current	V <sub>I/O</sub> < 0		-50 mA
I <sub>I/O</sub>	ON-state switch current <sup>(5)</sup>			±120 mA
Continuous current through V <sub>CC</sub> or GND				±100 mA
T <sub>stg</sub>	Storage temperature	-65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) V<sub>I</sub> and V<sub>O</sub> are used to denote specific conditions for V<sub>I/O</sub>.
- (5) I<sub>I</sub> and I<sub>O</sub> are used to denote specific conditions for I<sub>I/O</sub>.
- (6) The I/O pins are 5.5V tolerant and functional for the entire range. However, for V<sup>I/O</sup> > 3.6V, the channel RON is high (up to 100Ω).

### 5.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000 V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 <sup>(2)</sup>	±1500 V

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

See <sup>(1)</sup>.

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	2.3	3.6	V	
V <sub>IH</sub>	High-level control input voltage	V <sub>CC</sub> = 2.3V to 2.7V	0.46 × V <sub>CC</sub>	V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.7V to 3.6V			
V <sub>IL</sub>	Low-level control input voltage	V <sub>CC</sub> = 2.3V to 2.7V	0	0.25 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.7V to 3.6V			
V <sub>I/O</sub>	Data input/output voltage	0	5.5	V	
T <sub>A</sub>	Operating free-air temperature	-40	85	°C	

- (1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the [Implications of Slow or Floating CMOS Inputs](#) application note.

## 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TS3USB221		UNIT
		DRC (VSON)	RSE (UQFN)	
		10 PINS	10 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	57.7	204.8	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	87.7	118.1	
R <sub>θJB</sub>	Junction-to-board thermal resistance	32.6	121.5	
ψ <sub>JT</sub>	Junction-to-top characterization parameter	8.2	13.9	
ψ <sub>JB</sub>	Junction-to-board characterization parameter	32.8	121.2	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	18.5	N/A	

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

## 5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

PARAMETER	TEST CONDITIONS		MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>IK</sub>	V <sub>CC</sub> = 3.6V, 2.7V, I <sub>I</sub> = -18mA		-1.8			V
I <sub>IN</sub>	Control inputs	V <sub>CC</sub> = 3.6V, 2.7V, 0V, V <sub>IN</sub> = 0V to 3.6V			±1	μA
I <sub>OZ</sub> <sup>(3)</sup>		V <sub>CC</sub> = 3.6V, 2.7V, V <sub>O</sub> = 0V to 3.6V, V <sub>I</sub> = 0V, V <sub>IN</sub> = V <sub>CC</sub> or GND, Switch OFF			±1	μA
I <sub>OFF</sub>		V <sub>CC</sub> = 0V	V <sub>I/O</sub> = 0V to 3.6V		±2	μA
			V <sub>I/O</sub> = 0V to 2.7V		±1	
I <sub>CC</sub>		V <sub>CC</sub> = 3.6V, 2.7V, V <sub>IN</sub> = V <sub>CC</sub> or GND, I <sub>I/O</sub> = 0V, Switch ON or OFF			30	μA
I <sub>CC</sub> (low power mode)		V <sub>CC</sub> = 3.6V, 2.7V, V <sub>IN</sub> = V <sub>CC</sub> or GND, Switch disabled (OE in high state)			1	μA
ΔI <sub>CC</sub> <sup>(4)</sup>	Control inputs	One input at 1.8V, Other inputs at V <sub>CC</sub> or GND	V <sub>CC</sub> = 3.6V		20	μA
			V <sub>CC</sub> = 2.7V		0.5	
C <sub>in</sub>	Control inputs	V <sub>CC</sub> = 3.3V, 2.5V, V <sub>IN</sub> = 3.3V or 0V		1	2	pF
C <sub>io(OFF)</sub>		V <sub>CC</sub> = 3.3V, 2.5V, V <sub>I/O</sub> = 3.3V or 0V, Switch OFF		3	4	pF
C <sub>io(ON)</sub>		V <sub>CC</sub> = 3.3V, 2.5V, V <sub>I/O</sub> = 3.3V or 0V, Switch ON		5	6	pF
r <sub>on</sub> <sup>(5)</sup>		V <sub>CC</sub> = 3V, 2.3V	V <sub>I</sub> = 0V, I <sub>O</sub> = 30mA		6	Ω
			V <sub>I</sub> = 2.4V, I <sub>O</sub> = -15mA		6	
Δr <sub>on</sub>		V <sub>CC</sub> = 3V, 2.3V	V <sub>I</sub> = 0V, I <sub>O</sub> = 30mA		0.2	Ω
			V <sub>I</sub> = 1.7V, I <sub>O</sub> = -15mA		0.2	
r <sub>on(flat)</sub>		V <sub>CC</sub> = 3V, 2.3V	V <sub>I</sub> = 0V, I <sub>O</sub> = 30mA		1	Ω
			V <sub>I</sub> = 1.7V, I <sub>O</sub> = -15mA		1	

(1) V<sub>IN</sub> and I<sub>IN</sub> refer to control inputs. V<sub>I</sub>, V<sub>O</sub>, I<sub>I</sub>, and I<sub>O</sub> refer to data pins.

(2) All typical values are at V<sub>CC</sub> = 3.3V (unless otherwise noted), T<sub>A</sub> = 25°C.

(3) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.

(5) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

## 5.6 Dynamic Electrical Characteristics, $V_{CC} = 3.3V \pm 10\%$

 over operating range,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ ,  $V_{CC} = 3.3V \pm 10\%$ ,  $GND = 0V$ 

PARAMETER		TEST CONDITIONS	TYP <sup>(1)</sup>	UNIT
$X_{TALK}$	Crosstalk	$R_L = 50\Omega$ , $f = 250\text{MHz}$	-40	dB
$O_{IRR}$	OFF isolation	$R_L = 50\Omega$ , $f = 250\text{MHz}$	-41	dB
BW	Bandwidth (-3dB)	$R_L = 50\Omega$	1.1	GHz

- (1) For Maximum or Minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.

## 5.7 Dynamic Electrical Characteristics, $V_{CC} = 2.5V \pm 10\%$

 over operating range,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ ,  $V_{CC} = 2.5V \pm 10\%$ ,  $GND = 0V$ 

PARAMETER		TEST CONDITIONS	TYP <sup>(1)</sup>	UNIT
$X_{TALK}$	Crosstalk	$R_L = 50\Omega$ , $f = 250\text{MHz}$	-39	dB
$O_{IRR}$	OFF isolation	$R_L = 50\Omega$ , $f = 250\text{MHz}$	-40	dB
BW	Bandwidth (-3dB)	$R_L = 50\Omega$	1.1	GHz

- (1) For maximum or minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.

## 5.8 Switching Characteristics, $V_{CC} = 3.3V \pm 10\%$

 over operating range,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ ,  $V_{CC} = 3.3V \pm 10\%$ ,  $GND = 0V$ 

PARAMETER		MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{pd}$	Propagation delay <sup>(2) (3)</sup>		0.25		ns
$t_{ON}$	Line enable time	S to D, nD		30	ns
		$\overline{OE}$ to D, nD		17	
$t_{OFF}$	Line disable time	S to D, nD		12	ns
		$\overline{OE}$ to D, nD		10	
$t_{SK(O)}$	Output skew between center port to any other port <sup>(2)</sup>		0.1	0.2	ns
$t_{SK(P)}$	Skew between opposite transitions of the same output ( $t_{PHL} - t_{PLH}$ ) <sup>(2)</sup>		0.1	0.2	ns

- (1) For maximum or minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.
- (2) Specified by design
- (3) The bus switch contributes no propagational delay other than the RC delay of the on resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25ns for 10pF load. This time constant adds very little propagational delay to the system because the time is much smaller than the rise/fall times of typical driving signals. Propagational delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and the switch interactions with the load on the driven side.

## 5.9 Switching Characteristics, $V_{CC} = 2.5V \pm 10\%$

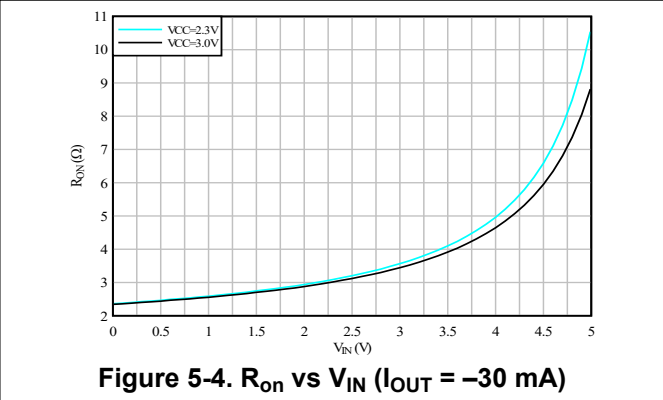
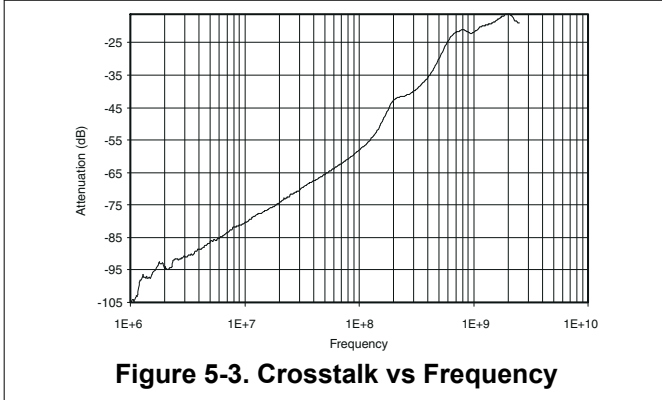
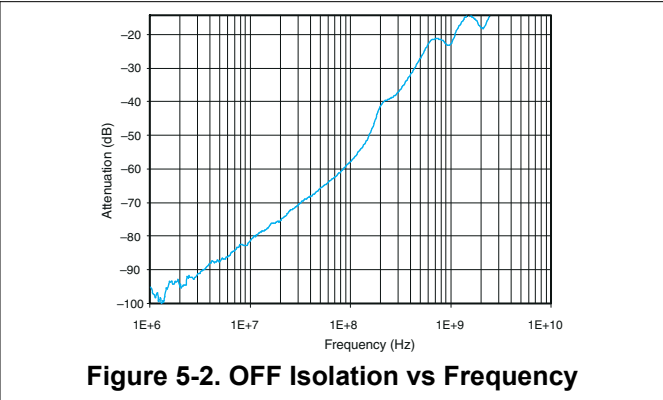
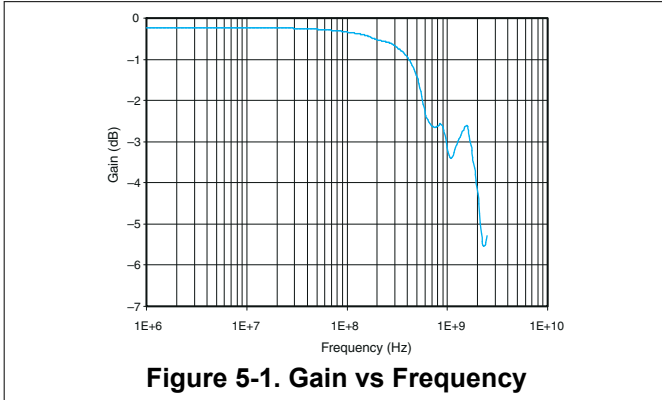
 over operating range,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ ,  $V_{CC} = 2.5V \pm 10\%$ ,  $GND = 0V$ 

PARAMETER		MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{pd}$	Propagation delay <sup>(2) (3)</sup>		0.25		ns
$t_{ON}$	Line enable time	S to D, nD		50	ns
		$\overline{OE}$ to D, nD		32	
$t_{OFF}$	Line disable time	S to D, nD		23	ns
		$\overline{OE}$ to D, nD		12	
$t_{SK(O)}$	Output skew between center port to any other port <sup>(2)</sup>		0.1	0.2	ns
$t_{SK(P)}$	Skew between opposite transitions of the same output ( $t_{PHL} - t_{PLH}$ ) <sup>(2)</sup>		0.1	0.2	ns

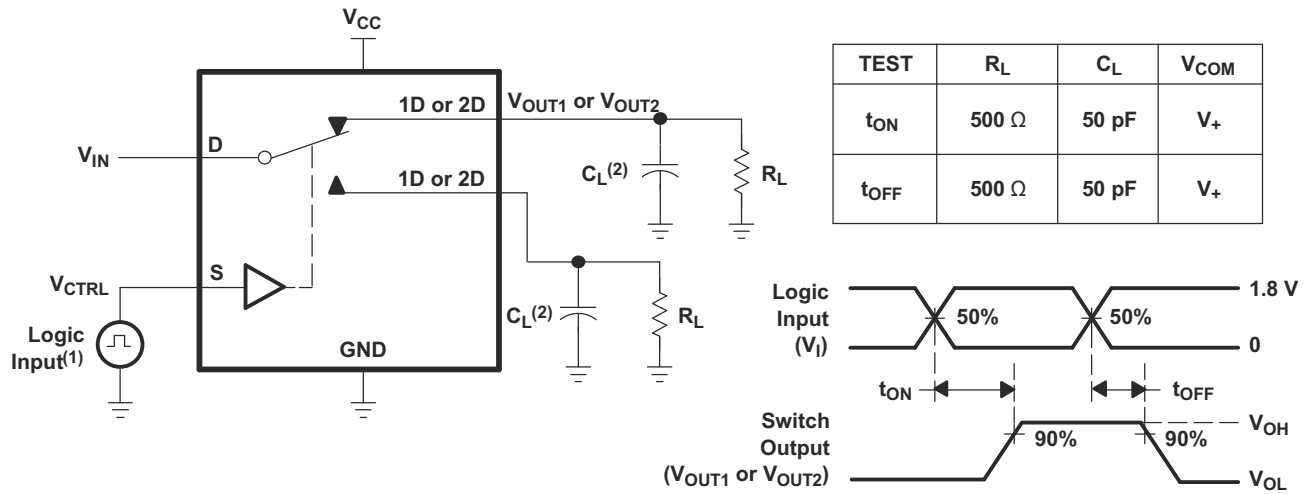
- (1) For maximum or minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.
- (2) Specified by design
- (3) The bus switch contributes no propagational delay other than the RC delay of the on resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25ns for 10pF load. The time constraint adds very little propagational delay

to the system because the time is much smaller than the rise and fall times of typical driving signals. Propagational delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and the switch interactions with the load on the driven side.

### 5.10 Typical Characteristics

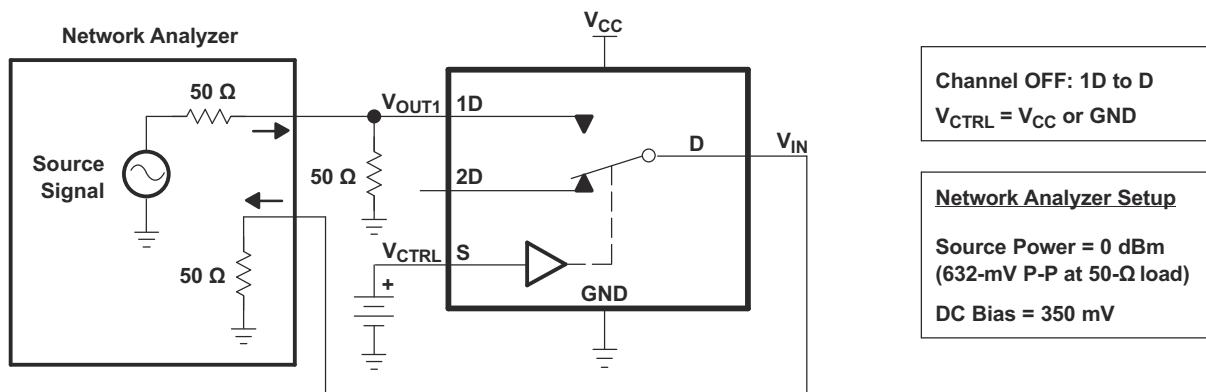


## 6 Parameter Measurement Information

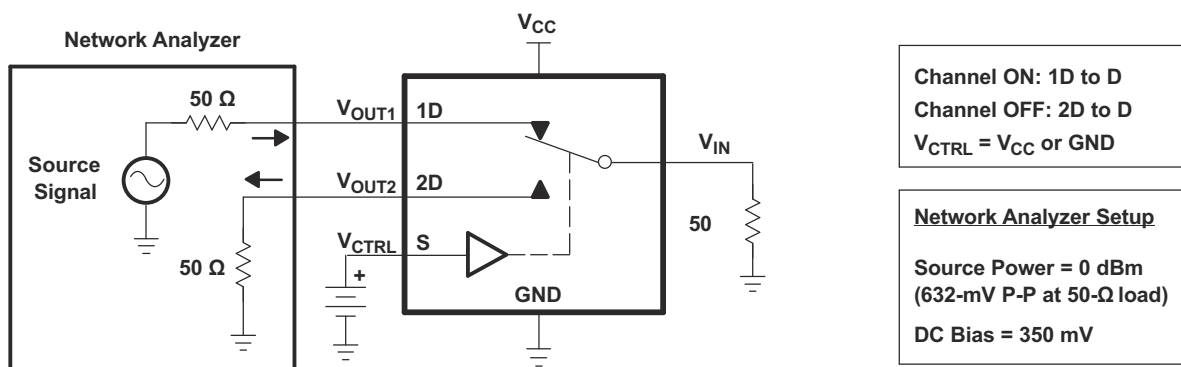


- (1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50Ω, t<sub>r</sub> < 5 ns, t<sub>f</sub> < 5 ns.  
 (2) C<sub>L</sub> includes probe and jig capacitance.

**Figure 6-1. Turnon (t<sub>ON</sub>) and Turnoff Time (t<sub>OFF</sub>)**

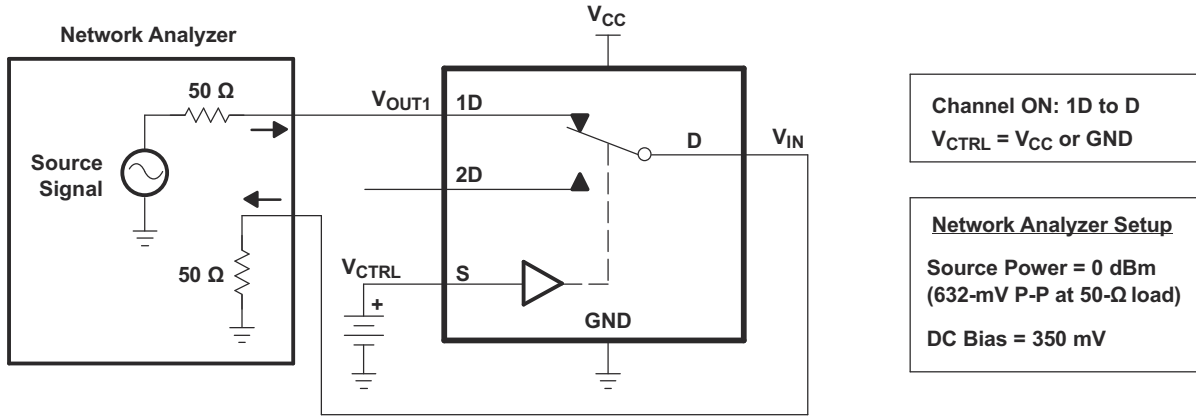


**Figure 6-2. OFF Isolation (O<sub>ISO</sub>)**

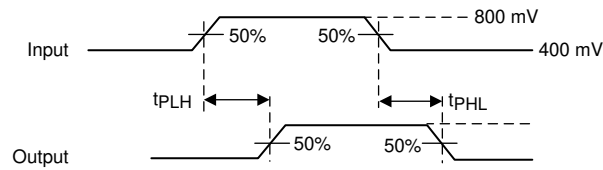


**Figure 6-3. Crosstalk (X<sub>TALK</sub>)**





**Figure 6-4. Bandwidth (BW)**



**Figure 6-5. Propagation Delay**

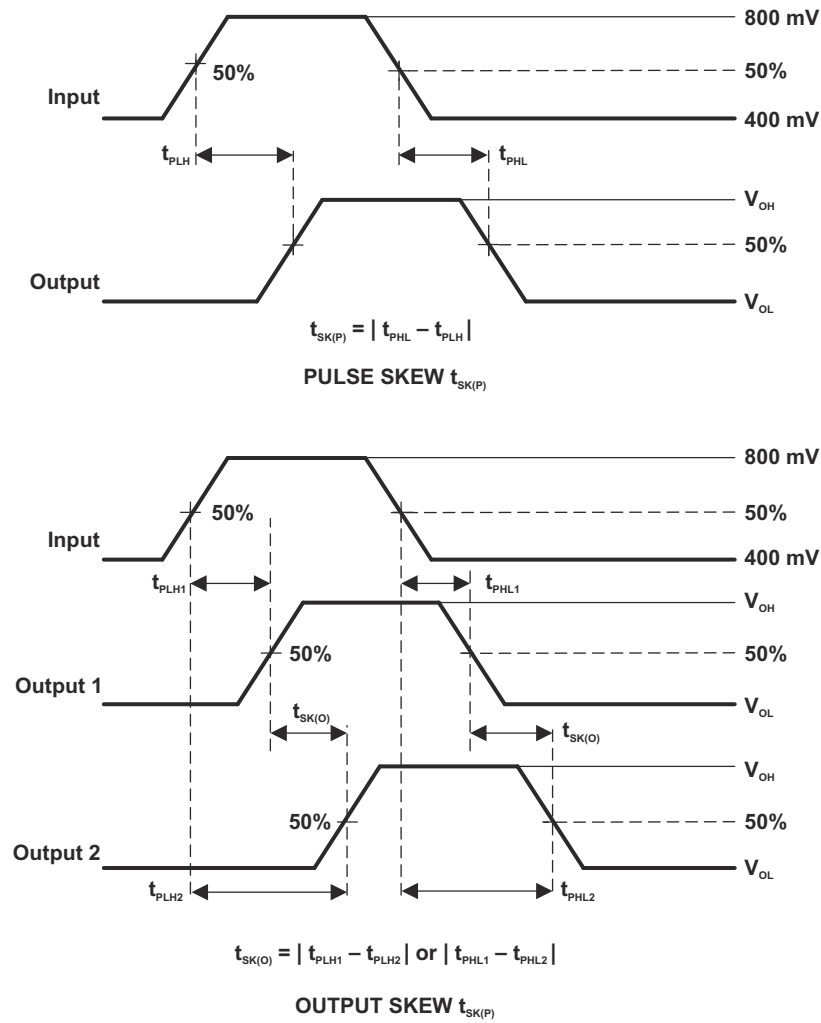


Figure 6-6. Skew Test

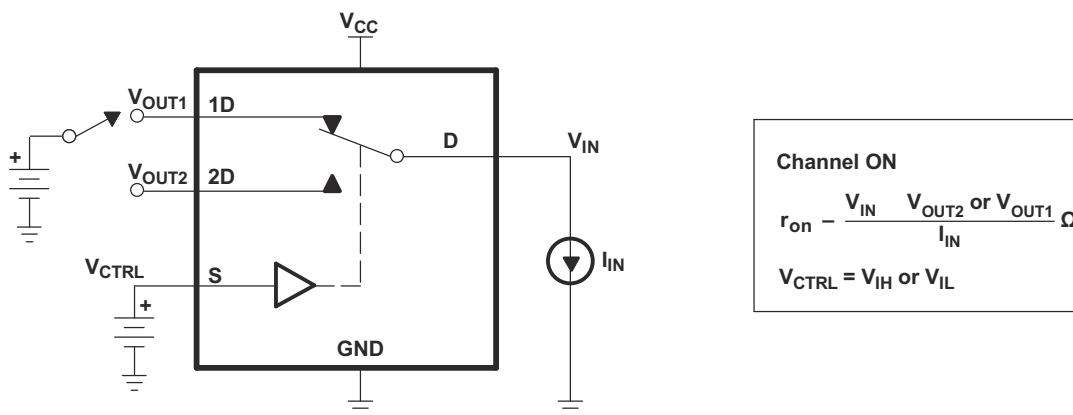
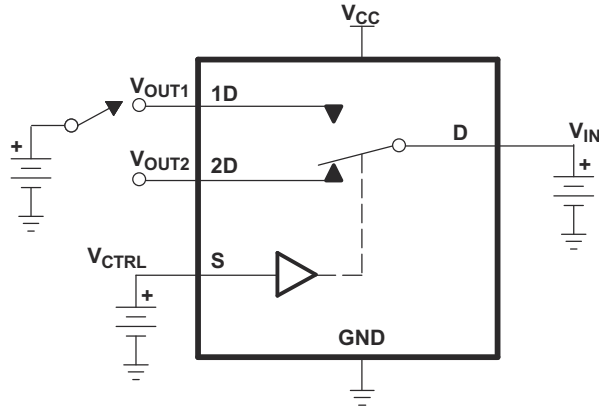
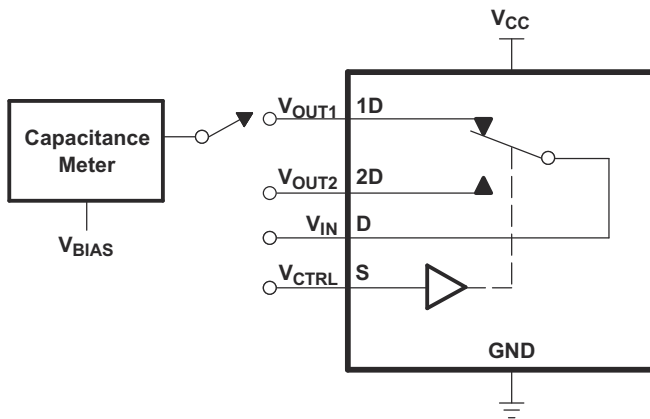


Figure 6-7. ON-State Resistance ( $r_{on}$ )



**OFF-State Leakage Current**  
 Channel OFF  
 $V_{CTRL} = V_{IH}$  or  $V_{IL}$

**Figure 6-8. OFF-State Leakage Current**



$V_{BIAS} = V_{CC}$  or  $GND$   
 $V_{CTRL} = V_{CC}$  or  $GND$   
 Capacitance is measured at 1D,  
 2D, D, and S inputs during ON  
 and OFF conditions.

**Figure 6-9. Capacitance**

## 7 Detailed Description

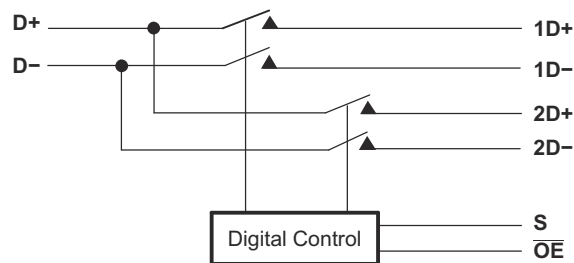
### 7.1 Overview

The TS3USB221 device is a 2-channel SPDT switch specially designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os. The wide bandwidth (1GHz) of this switch allows signals to pass with minimum edge and phase distortion. The device multiplexes differential outputs from a USB host device to one of two corresponding outputs. The switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. The device also has a low power mode that reduces the power consumption to 1  $\mu$ A for portable applications with a battery or limited power budget.

The device is designed for low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480Mbps).

The TS3USB221 device integrates ESD protection cells on all pins, is available in a SON package (3mm  $\times$  3mm) as well as in a tiny  $\mu$ QFN package (2mm  $\times$  1.5mm) and is characterized over the free-air temperature range from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

### 7.2 Functional Block Diagram



### 7.3 Feature Description

#### 7.3.1 Low Power Mode

The TS3USB221 has a low power mode that reduces the power consumption to 1  $\mu$ A when the device is not in use. The bus-switch enable pin OE must be supplied with a logic high signal to put the device in low power mode and disable the switch.

### 7.4 Device Functional Modes

Table 7-1. Truth Table

S	OE	FUNCTION
X	H	Disconnect
L	L	D = 1D
H	L	D = 2D

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

There are many USB applications in which the USB hubs or controllers have a limited number of USB I/Os. The TS3USB221 can effectively expand the limited USB I/Os by switching between multiple USB buses and interface with the buses on a single USB hub or controller. TS3USB221 can also be used to connect a single controller to two USB connectors.

### 8.2 Typical Application

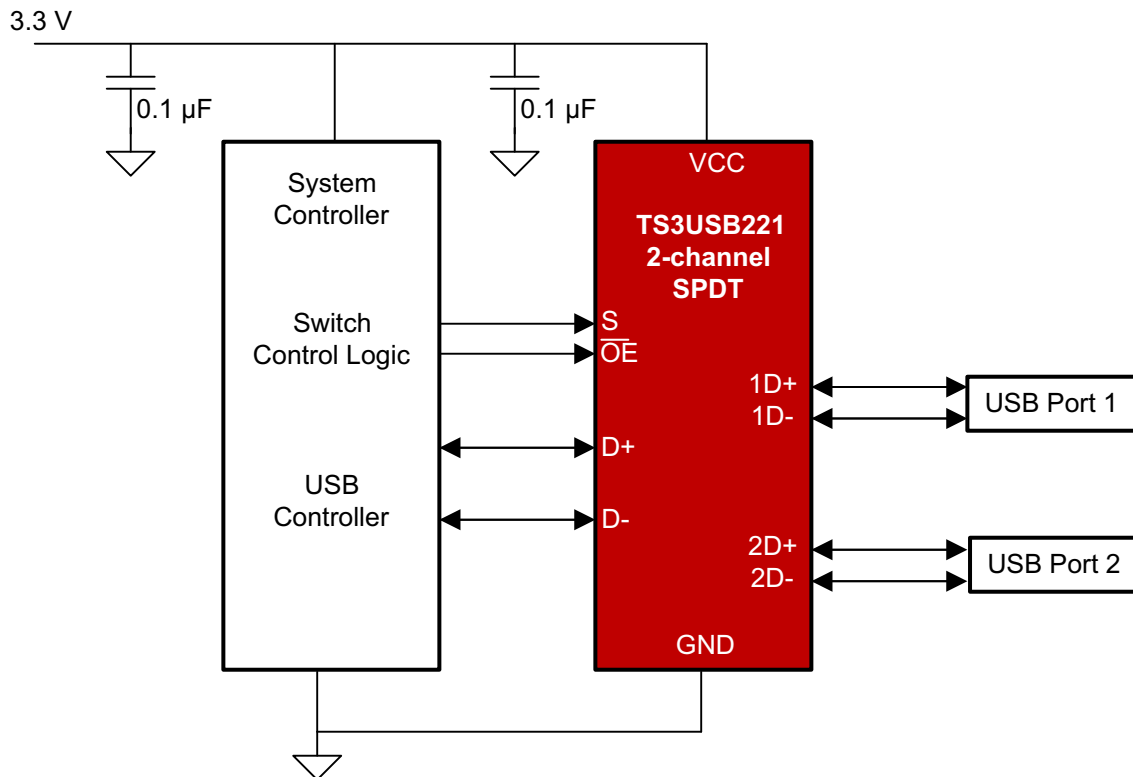


Figure 8-1. Simplified Schematic

#### 8.2.1 Design Requirements

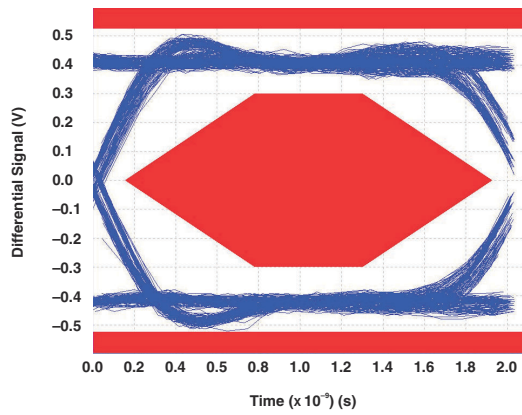
Follow the design requirements of the USB 1.0, 1.1, and 2.0 standards.

TI recommends that the digital control pins S and  $\overline{OE}$  be pulled up to  $V_{CC}$  or down to GND to avoid undesired switch positions that can result from the floating pin.

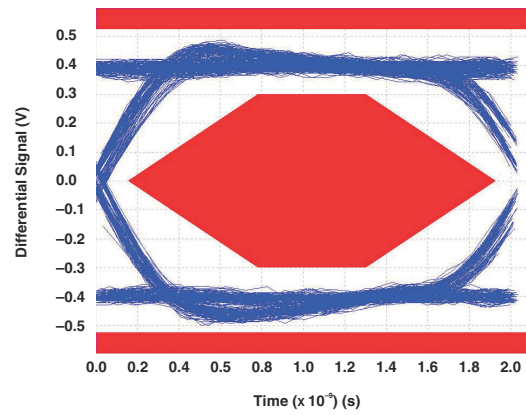
#### 8.2.2 Detailed Design Procedure

The TS3USB221 can operate properly without any external components. However, TI recommends to connect unused pins to ground through a  $50\Omega$  resistor to prevent signal reflections back into the device.

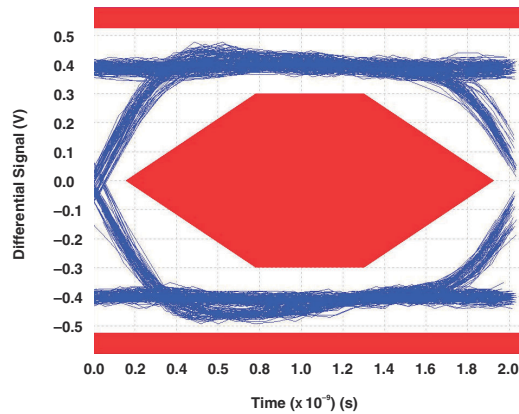
### 8.2.3 Application Curves



**Figure 8-2. Eye Pattern: 480Mbps USB Signal With No Switch (Through Path)**



**Figure 8-3. Eye Pattern: 480Mbps USB Signal With Switch NC Path**



**Figure 8-4. Eye Pattern: 480Mbps USB Signal With Switch NO Path**

### 8.3 Power Supply Recommendations

Make sure the power to the device is supplied through the  $V_{CC}$  pin and follows the USB 1.0, 1.1, and 2.0 standards. TI recommends placing a bypass capacitor as close as possible to the supply pin  $V_{CC}$  to help smooth out lower frequency noise to provide better load regulation across the frequency spectrum.

### 8.4 Layout

#### 8.4.1 Layout Guidelines

Place supply bypass capacitors as close to  $V_{CC}$  pin as possible. Avoid placing the bypass caps near the D+/D– traces.

Make sure the high-speed D+/D– trace lengths match and are no more than 4 inches, otherwise the eye diagram performance can degrade. A high-speed USB connection is made through a shielded, twisted pair cable with a differential characteristic impedance. In the layout, make sure the impedance of D+ and D– traces match the cable characteristic differential impedance for optimal performance.

Route the high-speed USB signals using a minimum of vias and corners to reduce signal reflections and impedance changes. When a via must be used, increase the clearance size around the via to minimize the capacitance. Each via introduces discontinuities in the transmission line of the signal and increases the chance of picking up interference from the other layers of the board. Be careful when designing test points on twisted pair lines; through-hole pins are not recommended.

When it becomes necessary to turn 90°, use two 45° turns or an arc instead of making a single 90° turn. This reduces reflections on the signal traces by minimizing impedance discontinuities.

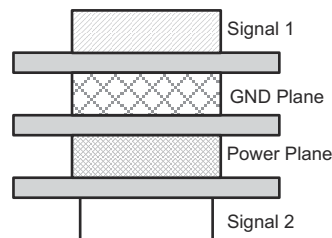
Do not route USB traces under or near crystals, oscillators, clock signal generators, switching regulators, mounting holes, magnetic devices or ICs that use or duplicate clock signals.

Avoid stubs on the high-speed USB signals because stubs cause signal reflections. If a stub is unavoidable, keep the stub less than 200mm.

Route all high-speed USB signal traces over continuous planes ( $V_{CC}$  or GND), with no interruptions.

Avoid crossing over anti-etch, commonly found with plane splits.

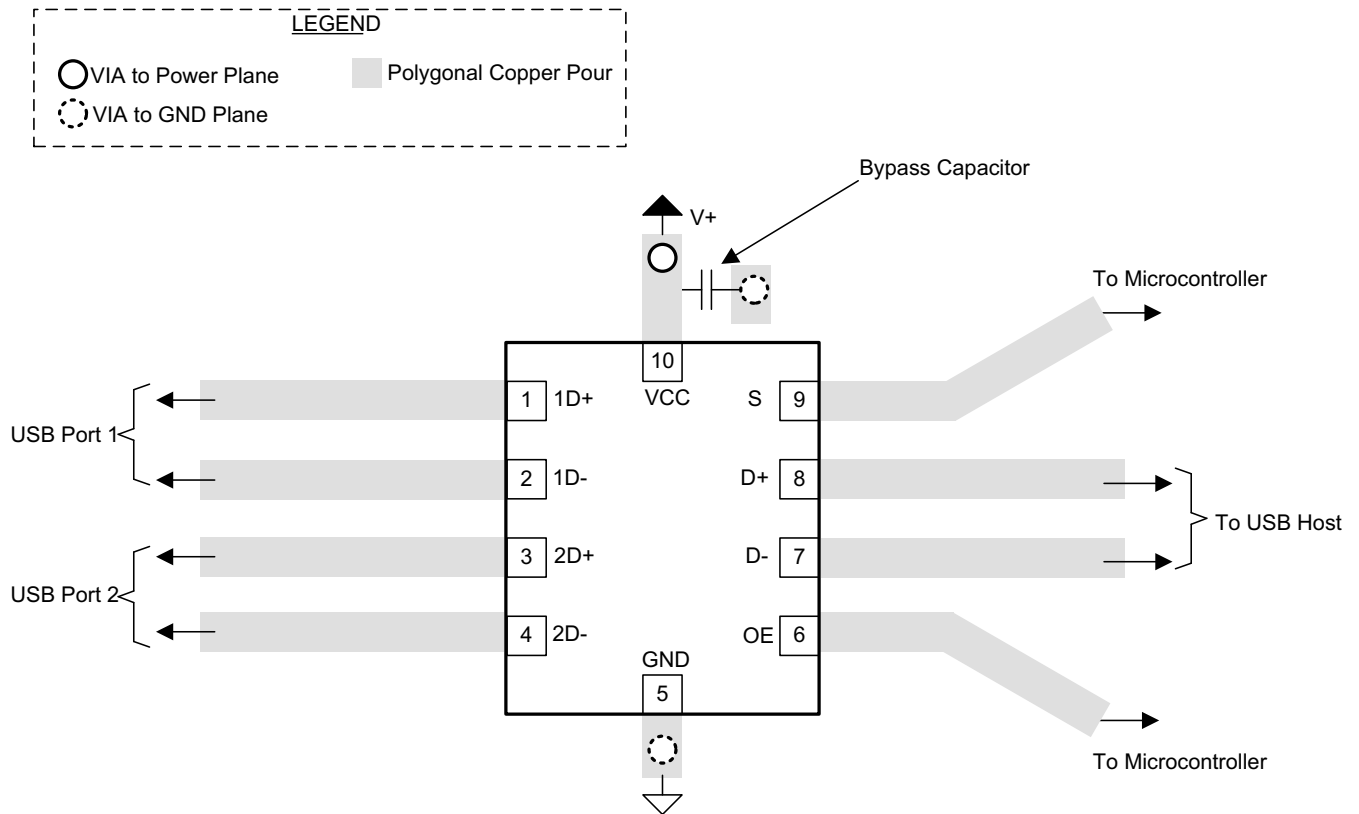
A printed circuit board with at least four layers is recommended because of high frequencies associated with the USB; two signal layers separated by a ground and power layer as shown in [Figure 8-5](#).



**Figure 8-5. Four-Layer Board Stack-Up**

Make sure the majority of signal traces run on a single layer, preferably Signal 1. Make sure the GND plane, which is solid with no cuts, is immediately next to this layer. Avoid running signal traces across a split in the ground or power plane. When running across split planes is unavoidable, sufficient decoupling must be used. Minimizing the number of signal vias reduces EMI by reducing inductance at high frequencies. For more information on layout guidelines, see [High Speed Layout Guidelines](#) and [USB 2.0 Board Design and Layout Guidelines](#).

### 8.4.2 Layout Example



**Figure 8-6. Package Layout Diagram**



## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [High Speed Layout Guidelines](#)
- Texas Instruments, [USB 2.0 Board Design and Layout Guidelines](#)
- Texas Instruments, [Implications of Slow or Floating CMOS Inputs application note](#)

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.4 Trademarks

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TI E2E™ is a trademark of Texas Instruments.

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### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision K (July 2024) to Revision L (October 2024)</b>	<b>Page</b>
• Changed <i>Features</i> bullet from: $R_{ON} = 6\omega$ maximum to: $R_{ON} = 6\Omega$ maximum.....	1
• Changed <i>Features</i> bullet from: $\delta r_{ON} = 0.2\omega$ typical to: $\Delta r_{ON} = 0.2\Omega$ typical.....	1

<b>Changes from Revision J (January 2019) to Revision K (July 2024)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed the typical bandwidth value from: 1.1GHz to: 1GHz.....	1
• Added footnote to the $V_{I/O}$ parameter in the <i>Absolute Maximum Ratings</i> table.....	4
• Changed CDM test conditions in the <i>ESD Ratings</i> table from: per JEDEC specification JESD22-C101 to: per ANSI/ESDA/JEDEC JS-002.....	4
• Changed RSE (UQFN) junction-to-ambient thermal resistance value from: 169.8°C/W to: 204.8°C/W.....	5
• Changed RSE (UQFN) junction-to-case (top) thermal resistance value from: 84.7°C/W to: 118.1°C/W.....	5

• Changed RSE (UQFN) junction-to-board thermal resistance value from: 94.9°C/W to: 121.5°C/W.....	5
• Changed RSE (UQFN) junction-to-top characterization parameter value from: 5.7°C/W to: 13.9°C/W.....	5
• Changed RSE (UQFN) junction-to-board characterization parameter value from: 94.9°C/W to: 121.2°C/W.....	5
• Changed the $V_{IK}$ value in the <i>Electrical Characteristics</i> table from: –1.8V maximum to: –1.8V minimum.....	5
• Changed the <i>Typical Characteristics</i> section.....	7

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<b>Changes from Revision I (January 2016) to Revision J (January 2019)</b>	<b>Page</b>
• Added CDM value and table notes to the ESD Ratings.....	4

---

<b>Changes from Revision H (February 2015) to Revision I (January 2016)</b>	<b>Page</b>
• Changed $V_{IH}$ Max from 5.5 to $V_{CC}$ in <i>Recommended Operating Conditions</i> table.....	4

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<b>Changes from Revision G (September 2010) to Revision H (February 2015)</b>	<b>Page</b>
• Changed first bullet of the Features FROM: $V_{CC}$ Operation at 2.5V and 3.3V TO: $V_{CC}$ Operation at 2.3V and 3.6V.....	1
• Added <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
• Removed the <i>Ordering Information</i> table.....	1

---

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN080104RSER	ACTIVE	UQFN	RSE	10	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L57, L5H, L5O, L5R, L5V)	<a href="#">Samples</a>
TS3USB221DRCR	ACTIVE	VSON	DRC	10	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZWG	<a href="#">Samples</a>
TS3USB221DRCRG4	ACTIVE	VSON	DRC	10	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZWG	<a href="#">Samples</a>
TS3USB221RSER	ACTIVE	UQFN	RSE	10	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L57, L5H, L5O, L5R, L5V)	<a href="#">Samples</a>
TS3USB221RSERG4	ACTIVE	UQFN	RSE	10	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L57, L5H, L5O, L5R, L5V)	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS3USB221DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TS3USB221RSER	UQFN	RSE	10	3000	180.0	9.5	1.7	2.2	0.75	4.0	8.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS3USB221DRCR	VSON	DRC	10	3000	356.0	356.0	35.0
TS3USB221RSER	UQFN	RSE	10	3000	189.0	185.0	36.0

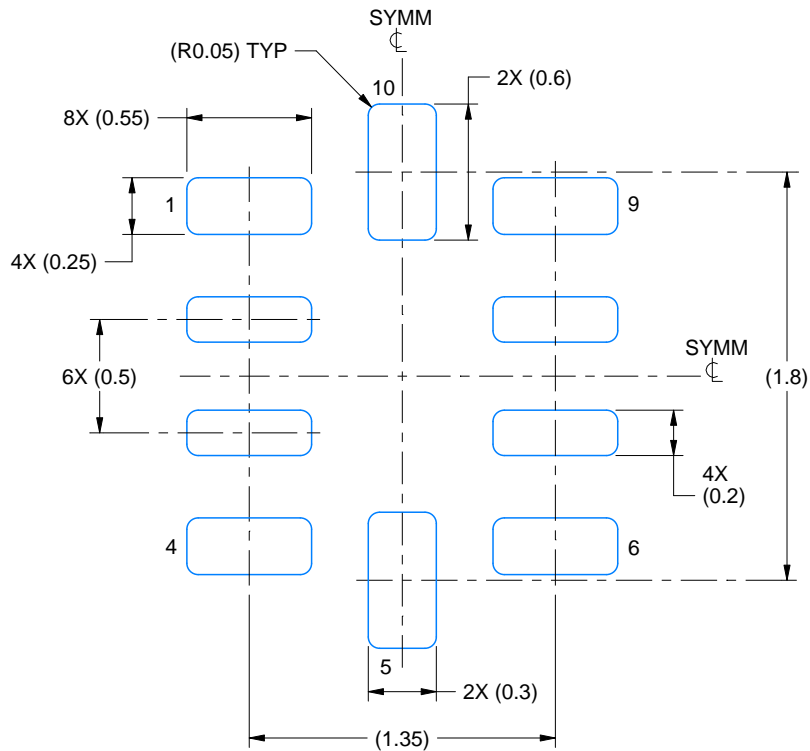


# EXAMPLE BOARD LAYOUT

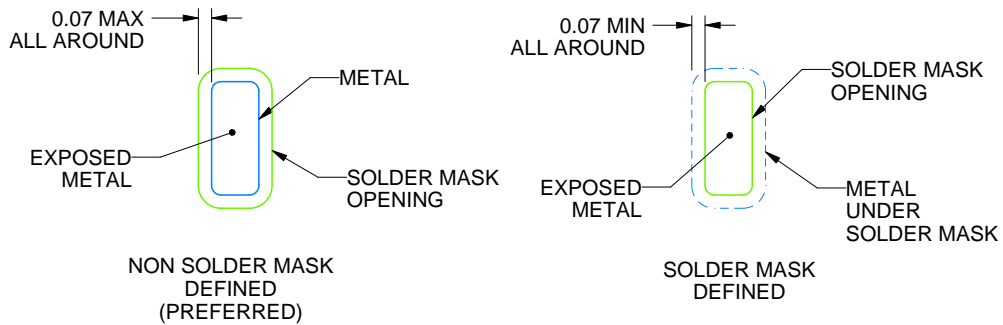
RSE0010A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:30X



SOLDER MASK DETAILS  
NOT TO SCALE

4220307/A 03/2020

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).





## GENERIC PACKAGE VIEW

**DRC 10**

**VSON - 1 mm max height**

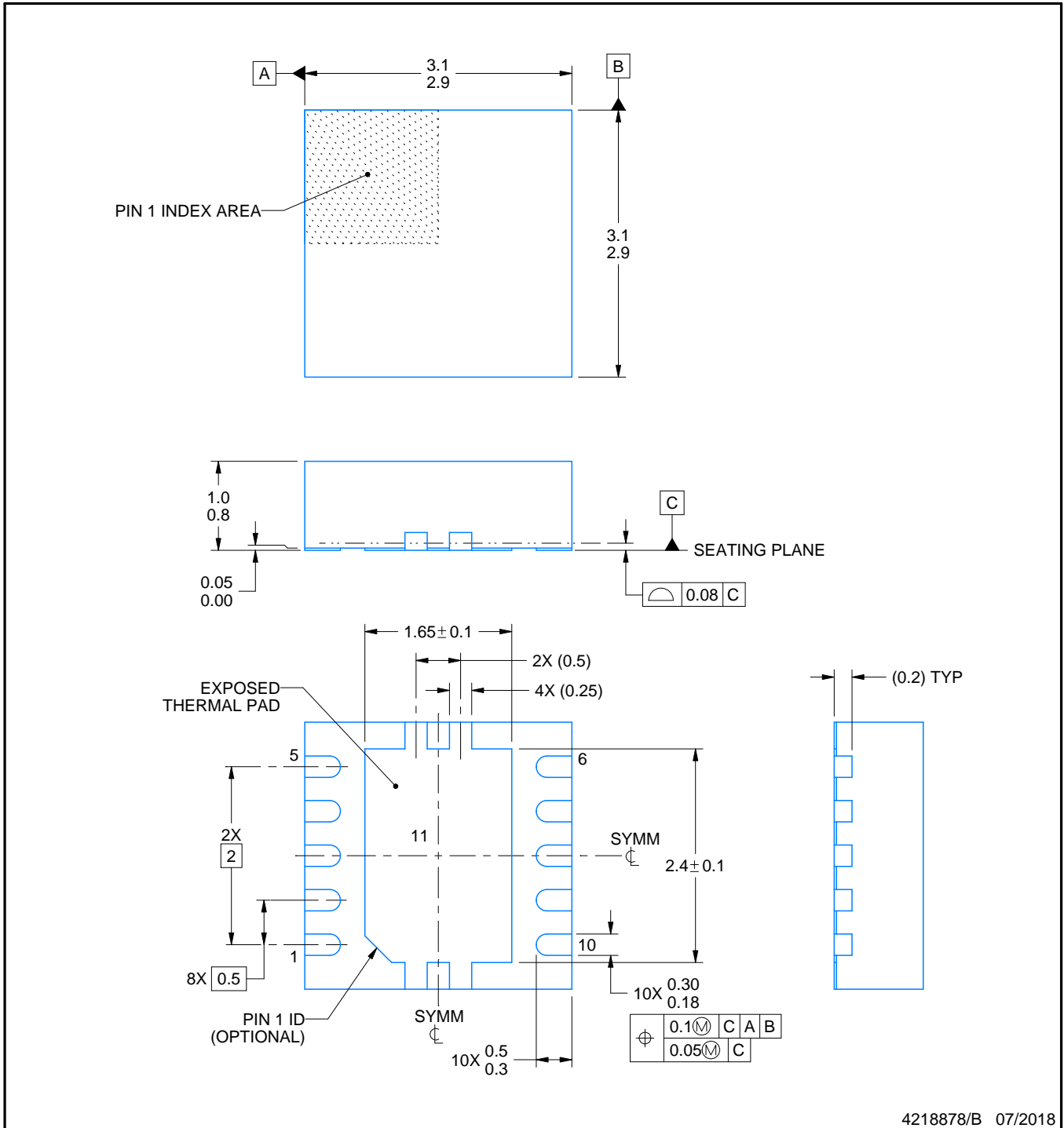
3 x 3, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4226193/A



4218878/B 07/2018

NOTES:

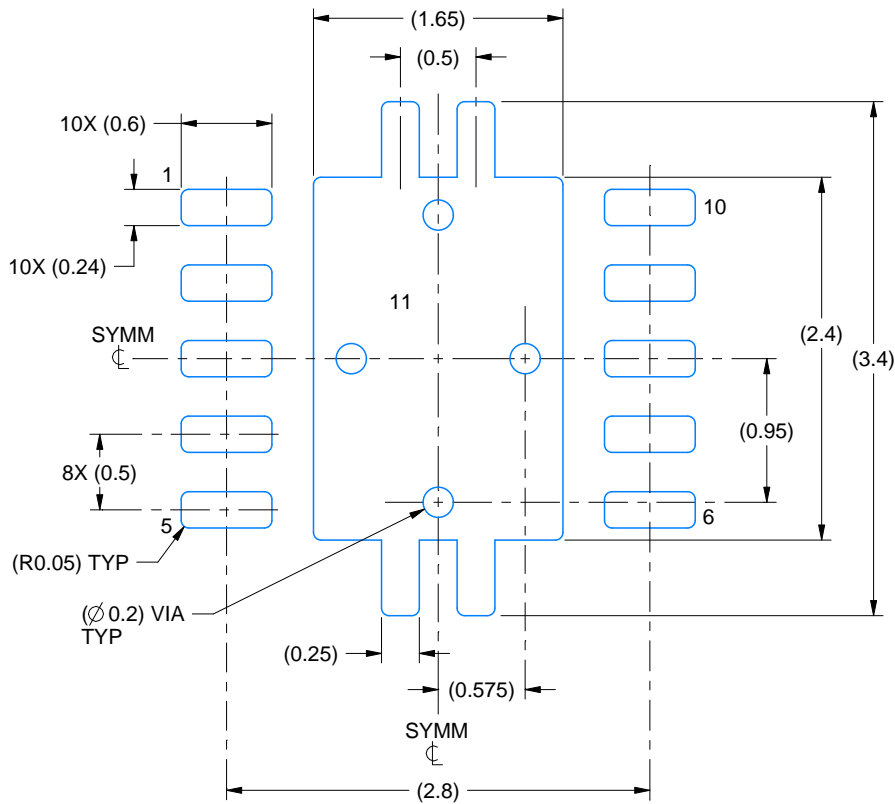
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

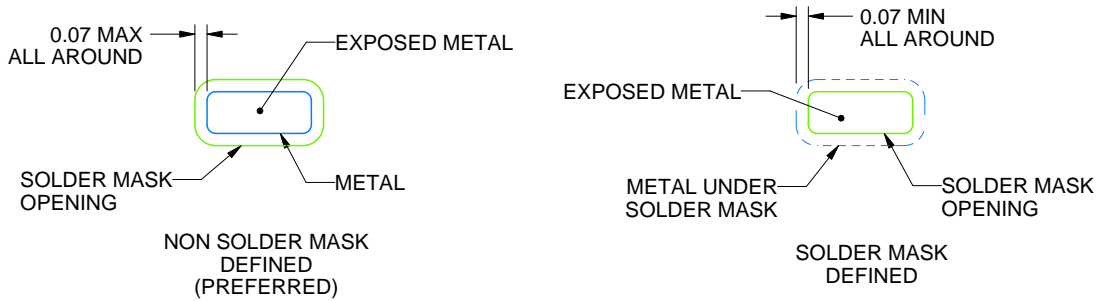
DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:20X



SOLDER MASK DETAILS

4218878/B 07/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:  
80% PRINTED SOLDER COVERAGE BY AREA  
SCALE:25X

4218878/B 07/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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